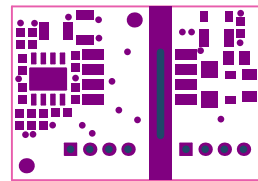
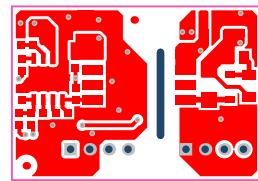


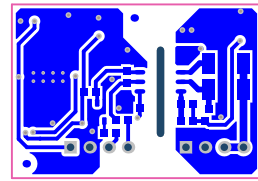
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01160	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01160		
PLOT NAME = Top Overlay	GENERATED : 5/2/2017 2:01:02 PM	TEXAS INSTRUMENTS	



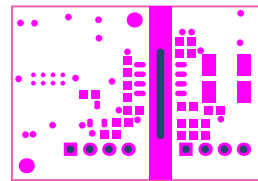
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01160	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01160		
PLOT NAME = Top Solder Mask	GENERATED : 5/2/2017 2:01:02 PM	TEXAS INSTRUMENTS	



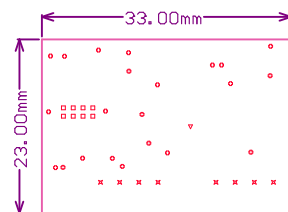
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01160	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01160		
PLOT NAME = Top Layer	GENERATED : 5/2/2017 2:01:03 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01160	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01160		
PLOT NAME = Bottom Layer	GENERATED : 5/2/2017 2:01:03 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01160	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01160		
PLOT NAME = Bottom Solder Mask	GENERATED : 5/2/2017 2:01:04 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Finished Hole Size	Plated	Hole Type	Physical Length	Rout Path Length
▽	1	39.37mil (1.000mm)	NPTH	Slot	472.44mil (12.000mm)	433.07mil (11.000mm)
□	8	7.87mil (0.200mm)	PTH	Round	-	-
⊗	8	39.37mil (1.000mm)	PTH	Round	-	-
⊕	22	15.00mil (0.381mm)	PTH	Round	-	-
	39 Total					

Slot definitions : Rout Path Length = Calculated from tool start centre position to tool end centre position.
 Physical Length = Rout Path Length + Tool Size = Slot length as defined in the PCB layout

DRILL TABLE
 FOR PTH +3/-3MIL
 FOR NPTH +2/-2MIL
 FOR 15MIL PTH +0/-15MIL
 FOR 7.87MIL PTH +0/-7.87MIL



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01160	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01160		
PLOT NAME = Drill Drawing	GENERATED : 5/2/2017	2:01:05 PM	TEXAS INSTRUMENTS

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